Improved crystalline structure and H₂S sensing performance of CuO-Au-SnO₂ thin film using SiO₂ additive concentration

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Abstract

In situ SiO₂-doped SnO₂ thin films were successfully prepared by liquid phase deposition. The influence of SiO₂ additive as an inhibitor on the surface morphology and the grain size for the thin film has been investigated. These results show that the morphology of SnO₂ film changes significantly by increasing the concentration of H₂SiF₆ solution which decreases the grain size of SnO₂. The stoichiometric analysis of Si content in the SnO₂ film prepared from various Si/Sn molar ratios has also been estimated. For the sensing performance of H₂S gas, the SiO₂-doped Cu-Au-SnO₂ sensor presents better sensitivity to H₂S gas compared with Cu-Au-SnO₂ sensor due to the fact that the distribution of SiO₂ particles in grain boundaries of nano-crystallines SnO₂ inhibited the grain growth (< 6 nm) and formed a porous film. By increasing the Si/Sn molar ratio, the SiO₂-doped Cu-Au-SnO₂ gas sensors (Si/Sn = 0.5) exhibit a good sensitivity (S = 67), a short response time ($t_{90\%}$ < 3 s) and a good gas concentration characteristic ($\alpha = 0.6074$). Consequently, the improvement of the nano-crystalline structures and high sensitivity for sensing films can be achieved by introducing SiO₂ additive into the SnO₂ film prepared by LPD method.

Keywords: Tin oxide, Liquid phase deposition, SiO₂ additive, H₂S sensor

1. Introduction

 SnO_2 is a semiconductor with a wide band-gap (Eg = 3.6 eV) that has been used in many important applications, including photoelectric devices [1], solar cells [2] and gas sensors [3–5]. The latter particularly benefit from SnO_2 thin film because of its structure, electrical properties and ability to detect various reducing gases, such as CO [6], ethanol [7] and H₂S [8-10]. Among of them, the hydrogen sulfide (H₂S) is a toxic gas produced from oil and natural gas, food processing and bacterial breakdown of organic matter or wastes produced by human and animal. The detection and monitoring of H₂S gas is important in the areas of oil and natural gas exploration, amenity of living environments and diagnosis in dentistry.

The sensing properties of SnO_2 sensors to H_2S gas have been shown to be influenced by many factors such as metal oxide additives, grain size and microstructure [11, 12]. In the metal oxide additives, most research and development of SnO2-besed H2S gas sensors are focused on Cu or Ag [5, 8-11], which utilize the heterocontacts between p-type CuO or Ag₂O and n-type SnO2 to form p-n junction and chemical affinity of CuO or Ag₂O to H₂S. When the additive-doped SnO₂ sensor exposes in H2S gas, the p-n junction is disrupted and the resistance of sensor drops down dramatically.

On the other hand, the SnO_2 sensing films tend increasingly to have nano-crystalline structures that usually are porous and have a relatively high specific surface area. The several interfaces between the nano-grains that interact with gas molecules effectively improve the diffusion properties while greatly increasing the sensitivity of the sensing film to gas. Accordingly, the effect of additives as inhibitors on the SnO_2 film have been studied by using various methods, such as sintered pastes [12], sol-gel [13, 14] and hydrothermal [15, 16].

In this study, the liquid phase deposition (LPD) was firstly used to deposit the SnO_2 film as gas sensing material, which nano-crystalline structures were improved by adding impurities in the treatment solution. Up to now, the LPD method has been widely applied to deposit many transition metal oxide films [17-19]; the preparation of which is based on the ligand-exchange hydrolysis of a metal-fluoro complex and an F⁻ consumption reaction with boric acid or aluminum metal.

The purpose of this study is to discuss the effect of SiO_2 as an inhibitor on the grain growth of SnO_2 film. In this paper, we report a SiO_2 -doped Cu-Au-SnO₂ H₂S sensor. The sensing material is made of introducing various

concentration of SiO₂ into the SnO₂ film during the liquid phase deposition. The proper amounts of Cu and Au as catalysts were coated on the SiO₂-doped SnO₂ surface by dip-coating method. The nanostructure of SiO₂-doped SnO₂ was characterized with X-ray diffraction (XRD), scanning electron microscopy (SEM), and atomic force microscopy (AFM). The stoichiometric analysis of Si content in the SnO₂ film prepared from various Si/Sn molar ratios has been estimated. The response properties of fabricated sensors to staircase concentration of H₂S and the recovery time in air have also been investigated and discussed.

2. Experimental

2.1 Deposition of SiO₂-doped SnO₂ film

LPD-SnO₂ thin films were prepared following the method given in Ref. [13]. Two substrates, oxidized silicon wafer and alumina, were used in this study. The starting reagent was SnF₂. The initial solution was prepared by dissolving SnF₂ powder in deionized (DI) water at room temperature with stirring, as the concentration was maintained at 0.1 M. The substrates were immersed vertically in the solution for ten hours at 60 °C with stirring to deposit the SnO₂ film.

SiO₂-doped SnO₂ films were prepared from growth solution at various Sn/Si molar ratios. First, excess silicic acid powder (SiO₂·*x*H₂O) was added to a commercial (RDH, Germany) 34 wt% hydrofluorosilicic acid (H₂SiF₆, 3.09 M) solution and thoroughly mixed by stirring for six hours to saturate at room temperature. After saturation, the undissolved silicic acid powders were filtered out using a 0.2 μ m Teflon filter. Then, the filtered 3.09 M saturated H₂SiF₆ solution was poured into the above 0.1 M SnF₂ solution. Growth solutions that contained three molar ratios of Si/Sn, 0.25, 0.33, and 0.5, were prepared. Before the substrates were immersed for deposition, various quantities of 0.5 M boric acid (H₃BO₃) were added with stirring and the molar ratio of boric acid to H₂SiF₆ in the growth solution was maintained at 2:1.

After ten hours of deposition, the substrate was removed, washed with DI water, and then dried at 70 °C. The calcination of films was carried out at the temperature varied from 300 to 700 °C with an increase of 100 °C for 1 hour in air.

The crystalline phase of the films was identified from grazing incident angle X-ray diffraction (Bede, D1) spectra obtained using Cu Ka radiation. The

surface roughness and morphology of the films were determined by scanning electron microscopy (Hitachi, S-4700I) and atomic force microscopy (Digital instrument, Dimension 3100). The chemical compositions of films were analyzed by high resolution X-ray photoelectron spectrometry (ULVAC-PHI, PHI Quantera SXM).

2.2 Fabrication of gas sensors and measurement of gas response characteristics

An alumina substrate with Au electrodes on both sides and RuO₂ on backside as a heater was prepared by screen-printing. The sensing area of the tin oxide was defined using a patterned photoresistor on the front of substrate whose backside was coated with the photoresistor as a passivation layer. Following deposition, the whole surface was covered with tin oxide. Then, the photoresistor was removed using acetone and a patterned SnO₂ was obtained by lift-off. After calcination of SnO₂ film at 600 °C for 1 hour in air, this polycrystallized films were immersed firstly in 2.5 mM cupric nitrate trihydrate (CuNO₃·3H₂O) solution for 20 seconds, pulled up slowly, and then dried at 60 °C in air, followed by calcination at 600 °C for 30 minutes in air. The doping process of Au catalyst was carried out similarly above in 30 mM hydrogen tetrachloraurate trihydrate (HAuCl₄·3H₂O), but the calcining temperature is at 350 °C. The calcination temperatures of catalysts were based on the results of thermal gravimetric analysis of the catalyst as shown in Fig. 1.

The sensor chips were wire bonded and suspended in air using Pt-wires. To determine the gas-sensing properties, the sensors were placed in a close chamber at room temperature and heated them up to a temperature between 250 and 300 °C. When H₂S was introduced into the chamber by using an injector and disturbed with a fan, the film resistance decreased. The response of each sensor to H₂S at constant concentration and the recovery time in air were measured by continuously recording the resistance of the sensor. In this study, the gas sensitivity was defined by $S = (R_a - R_g)/R_a$, where R_a and R_g are the electric resistances between Au electrodes before and after introduction of H₂S, respectively.

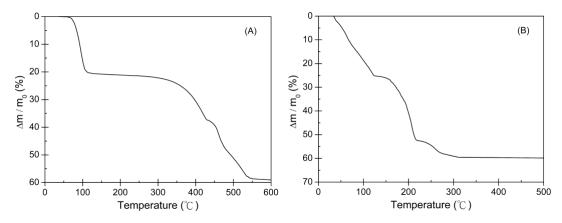


Fig. 1. The thermal gravimetric analysis curves: (A) $Cu(NO_3)_2 \cdot 3H_2O$, (B) $HAuCl_4 \cdot 3H_2O$.

3. Results and discussion

3.1 Microstructure of thin films

Figure 2(a) shows the grazing incident angle X-ray diffraction (GIAXRD) patterns of SnO₂ films that were calcined at various temperatures for 1 hour in air. The diffraction peak from the (110) crystal face was the largest, and the ratio between its intensity and those of the reflex intensities of the (101) and (211) faces agrees with the pattern of the tetragonal stannic oxide crystal [20]. The patterns indicate that the thin films belong to the rutile phase of SnO_2 . Figure 2(b) shows the effect of adding H_2SiF_6 on the diffraction peaks of the SnO₂ film. The half-width of the diffraction peaks in SiO₂-doped SnO₂ films increases with the Si/Sn molar ratio. At Si/Sn molar ratio of 0.5, effective grain growth inhibiting was clearly observed by much less peak sharpening as compared to the pure SnO₂ film and all the diffraction peaks also match with rutile phase. This result indicates that the SiO₂-doped SnO₂ film contains smaller grains than a pure SnO₂ film. Figure 3 plots the grain sizes of pure SnO₂ and SiO₂-doped SnO₂ films prepared at various Si/Sn molar ratios as functions of calcination temperature. Here, the grain size is estimated using the following equation, Eq. (1), from the half-width of the (110) diffraction peak based on the assumption that peak broadening occurs mainly because of the size effect [21].

$$D_{110} = 0.9 l / b_{1/2} \cos q \tag{1}$$

where D_{110} denotes the grain size, I = 1.541 Å, $b_{1/2}$ is the half-width of the (110)

diffraction peak, and q is the diffraction angle. The grains grow with the calcination temperature, but become more torpidly as the Si/Sn molar ratio increases. This result proves that doping with SiO₂ can effectively inhibit the grain growth of SnO₂.

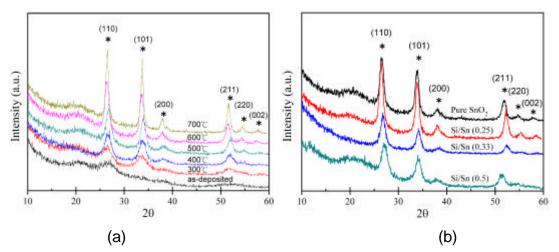


Fig. 2. X-Ray diffraction patterns of SnO₂ films: (a) pure SnO₂ films calcined at various temperatures, (b) pure SnO₂ and SiO₂-doped SnO₂ thin films calcined at 600 $^{\circ}$ C for 1 hour in air as a function of the molar ratio of Si/Sn.

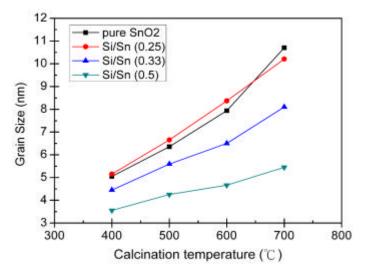


Fig. 3. The grain sizes of SnO₂ films prepared at various Si/Sn molar ratios as a function of calcination temperature.

Figure 4 shows SEM micrographs of SnO₂ films that were deposited on oxidized silicon substrate from various concentrations of H_2SiF_6 . Based on previous experimental results, the films were calcined at 600 °C for 1 hour in air [22]. It is note that the as-deposited SnO₂ film prepared by LPD contain fluorine element that could be removed completely when the calcination

temperature was arrived at 600 °C and formed a pure SnO₂ film. The surface morphology and porosity of SnO₂ films were clearly varied with the Si/Sn molar ratio as shown in Fig. 4. The parameters of fabrication of the SnO₂ film were set as above, and a uniform and dense SnO₂ film was formed on the substrate surface without adding H₂SiF₆, as shown in Fig. 4(a). On the other hand, when the H₂SiF₆ solution was added into the growth solution, the Si species that were derived from the H₂SiF₆ solution agglomerated with Sn species and formed a porous SnO₂ film during the liquid phase deposition. The SiO₂-doped SnO₂ film was constructed of non-uniform particles with different sizes as shown in Fig. 4(b). This result suggests that the SiO₂-doped SnO₂ film is suitable for fabricating gas sensors because it is porous with a large surface area [10, 23].

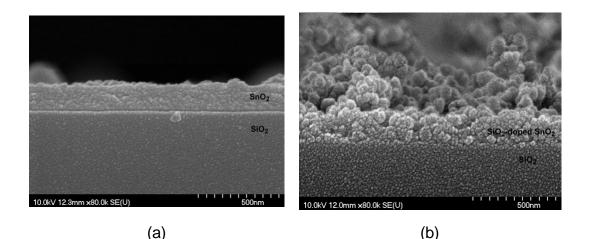


Fig. 4. SEM micrographs of SnO_2 films deposited from various concentrations of H_2SiF_6 after calcination at 600 °C for 1 hour in air. (a) pure SnO_2 and (b) Si/Sn (0.5).

Figure 5 shows the AFM photographs of SnO₂ films deposited from various concentrations of H₂SiF₆ and calcined at 600 °C for 1 hour in air. The surface morphology of pure SnO₂ film revealed a uniform particle size and high surface coverage (mean pore size is 43 nm), as shown in Fig. 5(a). For SiO₂-doped SnO₂ film, the particle size of the doped film exhibited non-uniformly distribution on the substrate surface. At Si/Sn molar ratio of 0.5, the porous structure was formed obviously by the particles (150~250 nm in size) contacted each other to form a large pores (126 nm average in size), and the grain size of SnO₂ tended to inhibit the grain growth of SnO₂ and enhanced the porosity of SnO₂ film. Furthermore, the surface roughness of the film

increased with the concentration of H_2SiF_6 solution, as shown in Figs. 5(b), consistent with the SEM results shown in Fig. 4(b).

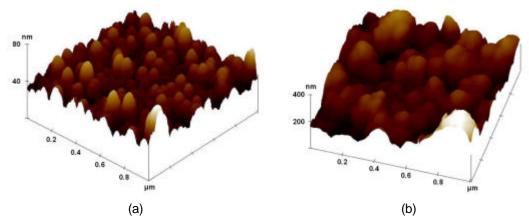


Fig. 5. AFM photographs of SnO_2 films deposited from various concentrations of H_2SiF_6 after calcination at 600 °C for 1 hour in air. (a) pure SnO_2 and (b) Si/Sn (0.5).

3.2 Stoichiometric analysis of thin films

The surface compositions of the SiO₂-doped SnO₂ films were analyzed by high resolution X-ray photoelectron spectroscopy (HRXPS). To generate atomic percentage values, each raw XPS signal must be corrected by dividing its signal intensity (number of electrons detected) by a relative sensitivity factor (RSF) and normalized over all of the elements detected [24], as given in Table 1. The analysis reveals that the atomic concentration of Si was very small (1%~2.5%) in the SnO₂ films that were deposited from Si/Sn molar ratio at 0.25~0.33. However, when the molar ratio was increased to 0.5, the atomic concentration of Si increased considerably to 6.75 %.

LPD SnO ₂ thin film	Atomic concentration				
	Sn (%)	Si (%)	O (%)	AI (%)	Total (%)
Pure SnO ₂	31.54	0	68.46	0	100
Si/Sn(0.25)	31.26	1.36	67.38	0	100
Si/Sn(0.33)	29.03	2.44	68.53	0	100
Si/Sn(0.5)	25.38	6.75	67.87	0	100

Table 1. Surface compositions of the deposited films

Figure 6 shows the results of the depth profile analysis (after correction for the atomic sensitivity factors) of the SnO_2 films prepared from H_2SiF_6 solution at various concentrations as a function of the sputtering time. It reports the O,

Sn, Si and Al elemental concentration in the films. For measurement purposes, since the amount of elemental Si in the doped films was very small, alumina was used as a substrate in place of the silicon wafer to prevent the HRXPS analysis results from being influenced by the Si substrate background signal. In Figs. 6, we observed that before the sputtering, the investigated LPD SnO₂ film consists of two dominant contributions: Sn and O corresponding to the pure SnO₂. When the SiO₂ introduced in the SnO₂ film, the film consists of three dominant contributions: Sn, Si and O corresponding to the mixture SnO₂ and SiO_2 as given in Table 1. The depth profile of the SnO_2 film (without SiO_2) clearly reveals that the atomic concentration of the Si did not change by increasing sputtering time, as shown in Fig. 6(a). In Figs. 6(b)–(c), the depth profiles of SiO₂-doped SnO₂ films prepared from Si/Sn molar ratios of 0.25 and 0.33 show that the amplitude of Si signal was increased slightly and contained only a small amount (1%–3%) in the SnO₂ film. This result indicated that the Si elements were uniformity dispersed in SnO₂ film. On the other hand, the atomic concentration of the Si changed considerably (about ~ 15 %) when the molar ratio reached 0.5, as shown in Fig. 6(d). These results show that various concentration of the Si atomic in the SnO₂ film could be obtained by controlling the Si/Sn molar ratio which confirmed that the Sn and Si elements were simultaneously present throughout the SnO₂ film during deposition.

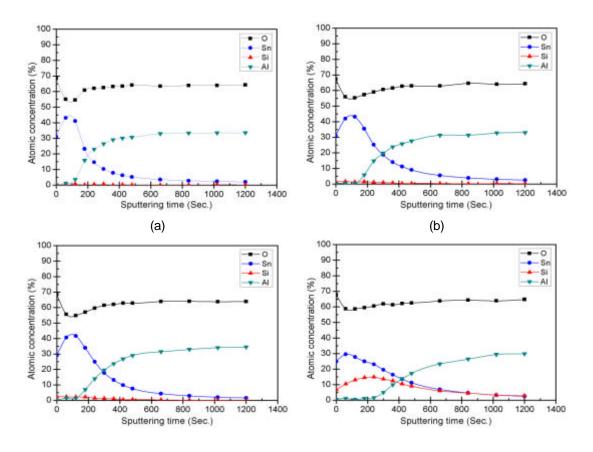


Fig. 6. Atomic concentration of O, Sn, Si and Al in sensing film as a function of the sputtering time: (a) pure SnO_2 , (b) Si/Sn (0.25), (c) Si/Sn (0.33) and (d) Si/Sn (0.5).

3.3 Response characteristics of gas sensors to H₂S

Figure 7 shows the effect of SiO₂ additive on the gas concentration characteristics of the SnO₂ gas sensor with catalysts Au and Cu. The response plots of the gas sensors operated at the temperature of 270 °C as a function of concentration of H₂S gas are straight lines on logarithmic scales. In this study, the sensors have wide spreads of absolute values of resistance during the sensing process, for it effectively normalizes the parameter, which can clearly show that the resistance changed with increasing gas concentration at various Si/Sn molar ratios. According to Fig. 7, the relationship between the resistance ratio (R_s/R_o) of the sensor (where R_o is the sensor resistance in 1 ppm H₂S and R_s is the sensor resistance in various H₂S concentration) and the gas concentration can be expressed by the following equation over a certain range of gas concentrations [20].

$$R_r = A \times C_s^{\ a} \tag{2}$$

where R_r denotes the resistance ratio (R_s/R_o) of the sensor, and C_s , A, and a denote gas concentration, a constant and the slope of the curve, respectively.

As shown in Fig. 7, since the differences in the resistance ratio R_r of each sensor responds to staircase concentration of H₂S gas were limited. By multiplying the multiple of 1 to 4 for sensors A to D, respectively, we can show the relationship between the R_r value and concentration of H₂S clearly. The result indicates that the value of α increased with the SiO₂ content derived from the H₂SiF₆ solution, suggesting that the SiO₂ additive affected the dependence of resistance on the gas concentration.

Figure 8 shows the sensitivity of sensors A to E, operated at 270 °C, to 2ppm H₂S gas. Experimental results indicated that the sensitivities of the sensors with catalysts Au and Cu were effectively enhanced by increasing the concentration of the SiO₂ additive. From this result, we concluded that the sensitivity of the sensors was increased due to the following two factors: (i) the target gas reacted with the catalyst, and (ii) the effective surface area of the sensor was exposed to ambiance of the target gas. The first factor was reported in a previous study [22], demonstrating that the catalysts Au and Cu

effectively enhance the sensitivity of sensors to H_2S gas. In this study, the CuO catalyst is used as a p-type semiconductor, which formed p-n junctions with the n-type SnO₂. The presence of these junctions leads to a higher resistive state of the sensor in air. When the sensor with CuO catalyst exposed to H_2S , CuO is converted to CuS. As CuS is an electronic conductance, which forming result in the destruction of p-n junctions and the resistance drops. When H_2S is turned off, CuS is quickly oxidized to CuO. The redox mechanism of the CuO catalyst is based on the reaction equation given as follows: [10, 25]:

$$CuO + H2S \rightarrow CuS + H2O$$
(3)

$$CuS + 3/2O_2 \rightarrow CuO + SO_2 \tag{4}$$

On the other hand, upon introducing Au catalyst to SnO_2 film, we are able to improve the drift response properties of gas sensor at long-term operation. As reported by Nelli et al. [26], cluster size and distribution of Au atoms in Au-doped SnO_2 film were not changed apparently after aging, which can be effectively limited the resistance drift of sensor during the long-term operation and consequently enhanced the long-term stability of sensor. In addition, according to Chiou et al. [22], an Au-doped SnO_2 film can also increase the sensitivity to H_2S gas. The increased sensitivity can be attributed to the partial oxidation of H_2S gas on the Au active metal and subsequent spillover of hydrogen atoms to the surface of SnO_2 substrate.

For the second factor, since the presence of the SiO₂ additive in a sensing film inhibited grain growth and effectively improved the surface areas of sensors B, C and D, agreeing with the XRD and SEM results herein. This result reveals that the sensors B to D have largest sensitivity than both sensor A and E at the concentration of 2ppm H_2S as shown in Fig. 8.

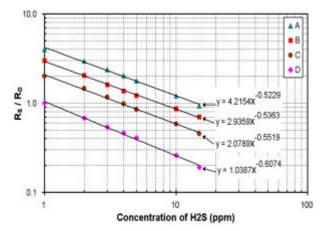


Fig. 7. Influence of SiO₂ additive on the gas concentration characteristics of the SnO₂-based gas sensors operated at 270 $^{\circ}$ C: (A) (Au, Cu)-doped SnO₂ film,

(B) (Au, Cu)-doped Si/Sn (0.25) film, (C) (Au, Cu)-doped Si/Sn (0.33) film and (D) (Au, Cu)-doped Si/Sn (0.5) film. *Ro*: sensor resistance in 1 ppm H_2S ; *Rs*: sensor resistance in various H_2S concentration.

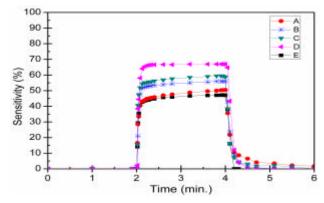


Fig. 8. The sensitivity to 2 ppm H₂S of sensors: (A) (Au, Cu)-doped SnO₂ film, (B) (Au, Cu)-doped Si/Sn (0.25) film, (C) (Au, Cu)-doped Si/Sn (0.33) film, (D) (Au, Cu)-doped Si/Sn (0.5) film and (E) pure SnO₂ film at 270 °C.

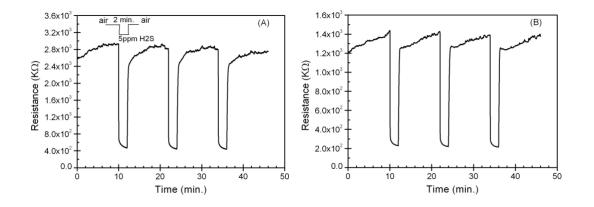
The microstructure of a sensing film, including grain size, affects its sensing response and electrical properties. In the present study, four sensors A, B, C and D were prepared from H_2SiF_6 solution at various concentrations and coated with Au and Cu catalyst, with grain sizes of 7.9, 8.4, 6.5 and 4.7 nm, respectively. For electrical properties of sensors, the changes in resistance of the sensors were greatly influenced by grain size. As the result shown in Fig. 9, which is denoted to sensor from A to D, it is found that the electric resistances of the sensors operated at 270 °C in air were changed by the effect of grain size. In this work, the effect of grain size on resistance of these sensors can be attributed to the factors of the neck-control and the grain-control [27]. For the sensors A to C, firstly, grain sizes of the sensors are larger than 2L (ca. 6nm) where L is the Debye length of SnO_2 . The SnO_2 grains in the sensor are connected each other and formed a neck mold (belong to the neck-control). In the case, conduction electrons move through a channel penetrating each neck, so that the neck size in each SnO₂ grain is dominated mainly the resistance of the sensor. Under this condition, a decline in grain size would lead to slightly higher resistance of a sensor. Therefore, the resistance of sensors A to C would be located at the same magnitude of order in clear air. On the other hand, the grain size of the sensor D is smaller than 2L. Because whole grains are now put inside the space charge region, which lead to the grain boundary potential was maintained at high potential barrier level in ambient air. Hence, the resistance of the sensor was governed by the resistance of grains (belong

to the grain-control). Otherwise, due to the amount of insulating SiO_2 additive in the sensor D is largest compared with sensor A to C and thus the resistance of sensor D was drastically increased. By comparing the resistance of these sensors in ambient air, it can be seen that the resistance magnitude of sensor D is two orders larger than sensor A to C as shown in Fig. 9.

Figure 9 plots their electrical responses to ambient air and 5 ppm H₂S gas at operating temperature of 270 °C. The results indicate that all of the sensors have highly reproducible and stable sensing characteristics during multiple cycles of sensing and recovery. Moreover, their electrical response is fast and highly reversible, during both sensing and recovery, and depends strongly on the grain size. Table 2 summarizes the 90 % times ($t_{90\%}$) for the response and recovery of sensors A to D. It reveals that the sensors respond very rapidly and their $t_{90\%}$ values were decreased by reducing the grain size. The results indicate that the grain size of the SnO₂ thin film affects the sensitivity and the response time.

Table 2. The response and recovery time of the SnO₂ sensors at operating temperature of 270 $^{\circ}$ C for the detection of 5 ppm H₂S.

Sample Number	Response time (<i>t</i> 90%:s)	Recovery time (<i>t</i> 90%:s)
Sensor A	31	101
Sensor B	19	19
Sensor C	4	13
Sensor D	<3	12



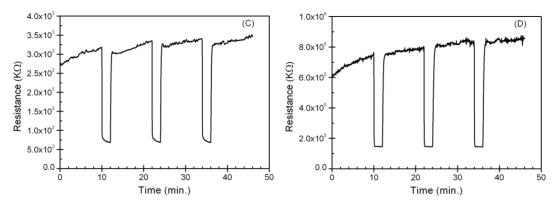


Fig. 9. The characteristics of response and recovery of sensors: (A) (Au, Cu) doped pure SnO₂, (B) (Au, Cu) doped Si/Sn (0.25), (C) (Au, Cu) doped Si/Sn (0.33) and (D) (Au, Cu) doped Si/Sn (0.5) to 5 ppm H₂S at 270 $^{\circ}$ C.

4. Conclusion

In this study, a fabrication method that is based on liquid phase deposition was proposed firstly to fabricate a nano-crystalline SnO₂ sensing film. From characterization investigation of the sensor material, it is can be seen that the morphology of SnO₂ film changes significantly by increasing the concentration of H₂SiF₆ solution which decreases the grain size of SnO₂. The final stoichiometric analysis of the sensing material indicated that various concentration of the Si element in the SnO₂ film can be obtained by controlling Si/Sn molar ratio. For the sensing performance of H₂S gas, the SiO₂-doped Cu-Au-SnO₂ sensor presents better sensitivity compared to Cu-Au-SnO₂ sensor due to the fact that the distribution of SiO₂ particles in grain boundaries of nano-crystallines SnO_2 inhibited the grain growth (< 6 nm) and formed a porous film. Experimental results indicated that the SiO₂-doped Cu-Au-SnO₂ gas sensors (Si/Sn = 0.5) exhibit a good sensitivity (S = 67 %) to 2 ppm H₂S, a short response time ($t_{90\%}$ < 3 s) and a good gas concentration characteristic (α = 0.6074). Finally, the improvement of the nano-crystalline structures and high sensitivity for sensing films can be achieved by introducing SiO₂ additive into the SnO₂ film prepared by LPD method.

Acknowledgements

The authors would like to thank Dr. C.T. Huang from Oriental System Technology, Inc., Hsinchu Science Park, Taiwan for suggestions in gas sensor designs and fabrications. This work was supported in part by the Raydium Semiconductor Corporation, Taiwan, R. O. C. (contract no. 098426N3),

Ministry of Education (contract no. 99W958) and Taiwan Department of Health Clinical Trial and Research Center of Excellence (contract no. DOH99-TD-B-111-004)

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